

Electronic Patent Application Fee Transmittal

Application Number:	10525996			
Filing Date:	28-Feb-2005			
Title of Invention:	Protective structure of semiconductor wafer, method for protecting semiconductor wafer, multilayer protective sheet used therein, and method for processing semiconductor wafer			
First Named Inventor/Applicant Name:	Hideo Senoo			
Filer:	Kent E. Baldauf/Dianne Kimak			
Attorney Docket Number:	1217-050618			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 3 months with \$120 paid	1253	1	930	930

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	810	810
Total in USD (\$)				1740